

*AM*  
advantages.

---

IN THE ABSTRACT

Kindly delete the present abstract and substitute therefor the new abstract presented herewith on a separate sheet.

IN THE CLAIMS

Kindly cancel claim 8, without prejudice, and amend claim 1 as follows:

*AG*  
*Sub 151*  
1. (amended) A multiple semiconductor chip (multi-chip) module, comprising at least a power semiconductor chip and a control semiconductor chip mounted on an electrically conductive heat sink, wherein said power semiconductor chip comprises a Silicon-On-Insulator (SOI) device and said control semiconductor chip comprises a bulk technology semiconductor device having a substrate connected to ground potential, and said power semiconductor chip and said control semiconductor chip are directly mounted on said electrically conductive heat sink without the use of a separate electrical insulation layer.

---